

Release Notes

Revision	Date	Description
1.0	2023/05/05	Initial issue
	2023/05/10	1.MCU/屏幕及触控 改为3V3,Audio部分改为MCU检测和控制 2.BT SOC GPIO13-19改为3V3电平，删除和修改部分IO net 3.机盒通信改为5P,单线串口与5V分离，增加DP/DM直连 4.电源树修改，BT SOC 3V3仅为USB MUX和PA供电，PA供电预留LDO。 5.HP AMP更换为SGM4917A，做兼容设计
	2023/05/12	1.增加SWD到MCU PA13/PA14。 2.BAT NTC电路修改，增加R92 上拉到SOC 1V8 3.RF Bypass改到GPIO11

Company: <Company>	
Project Name: WM301_RX	
Drawn by: LTW/Bob	Date: 2023-05-12
Sheet: 1 OF 4	Version: V1.0

Company: <Company>

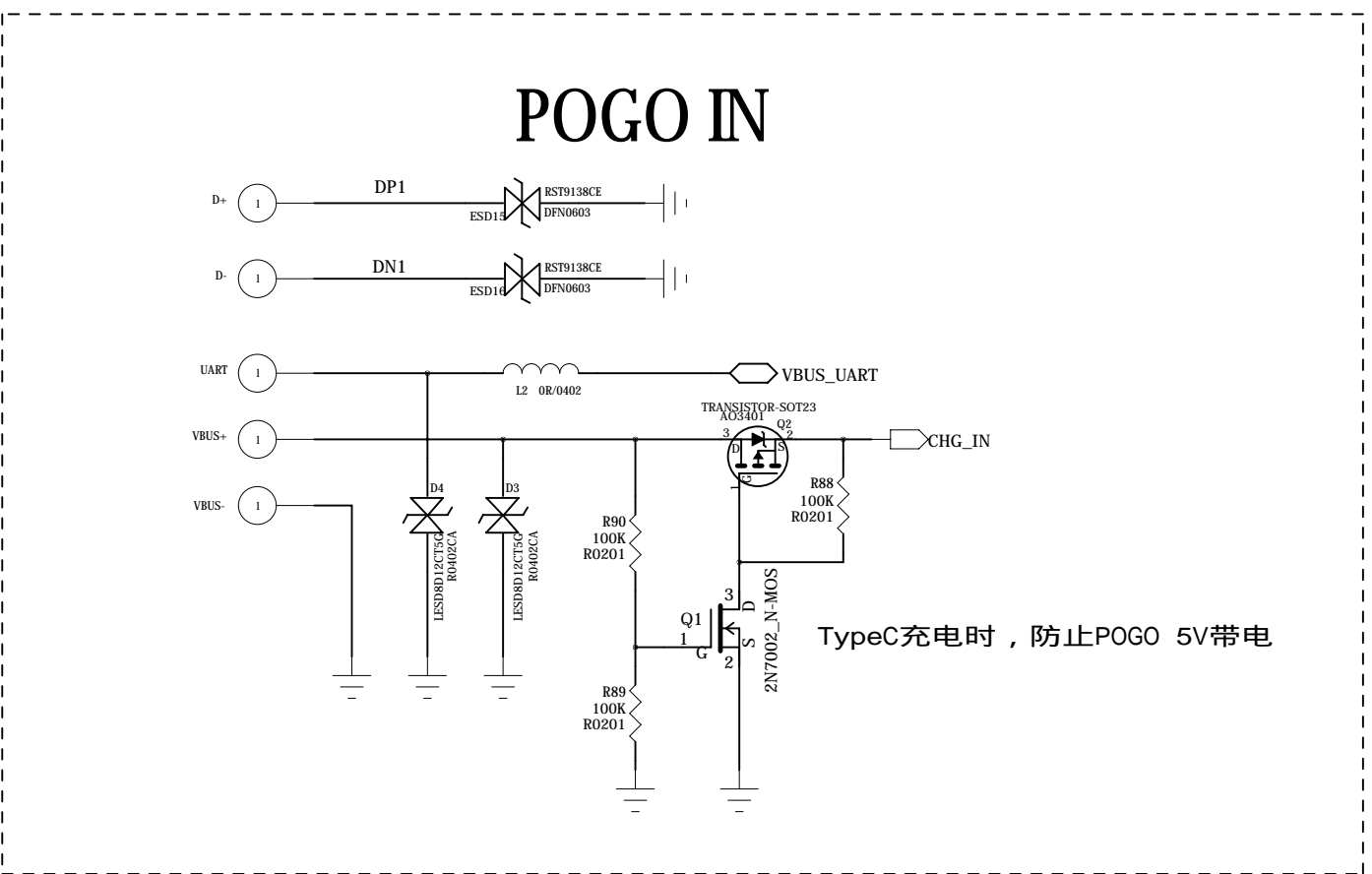
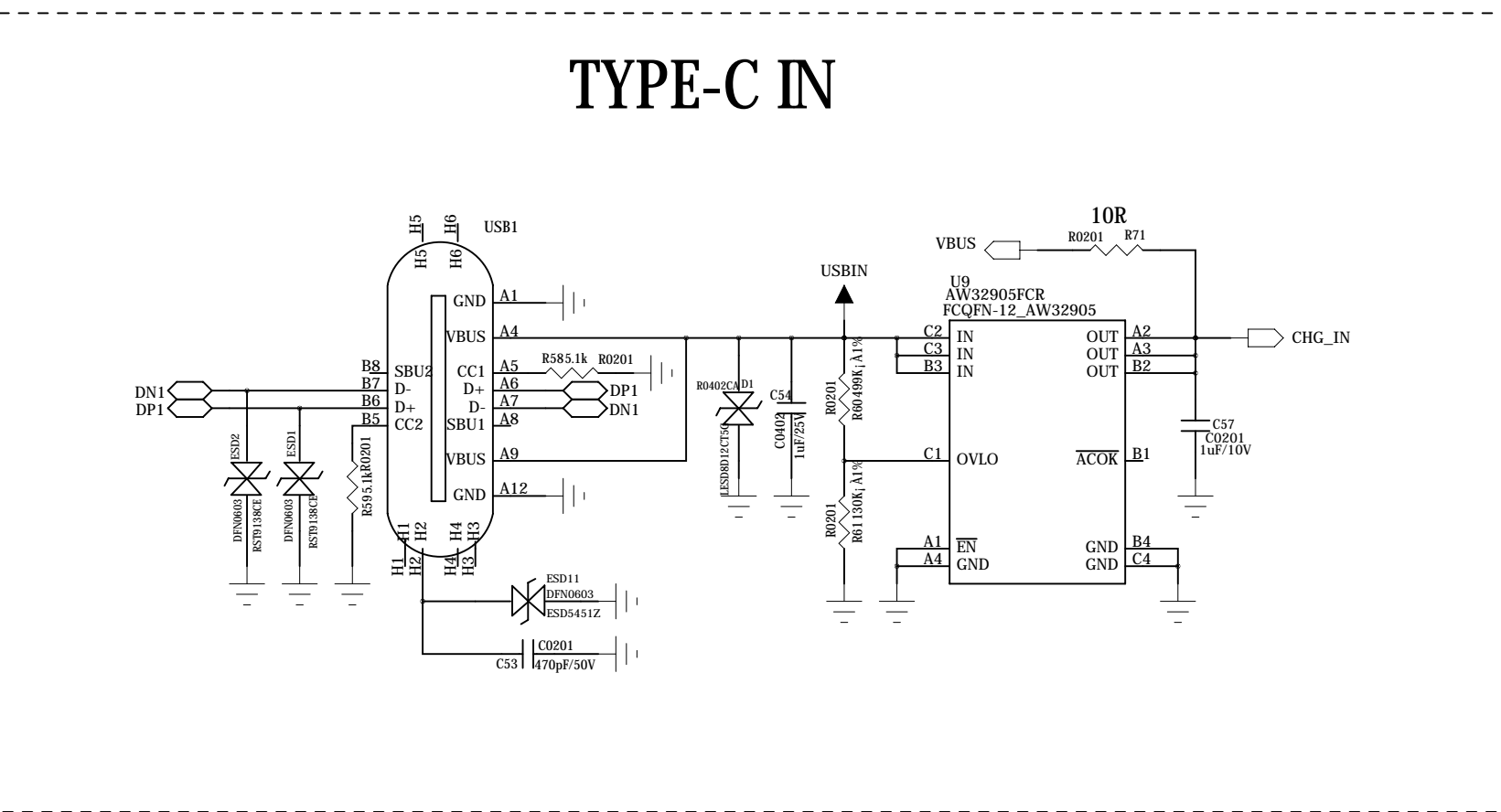
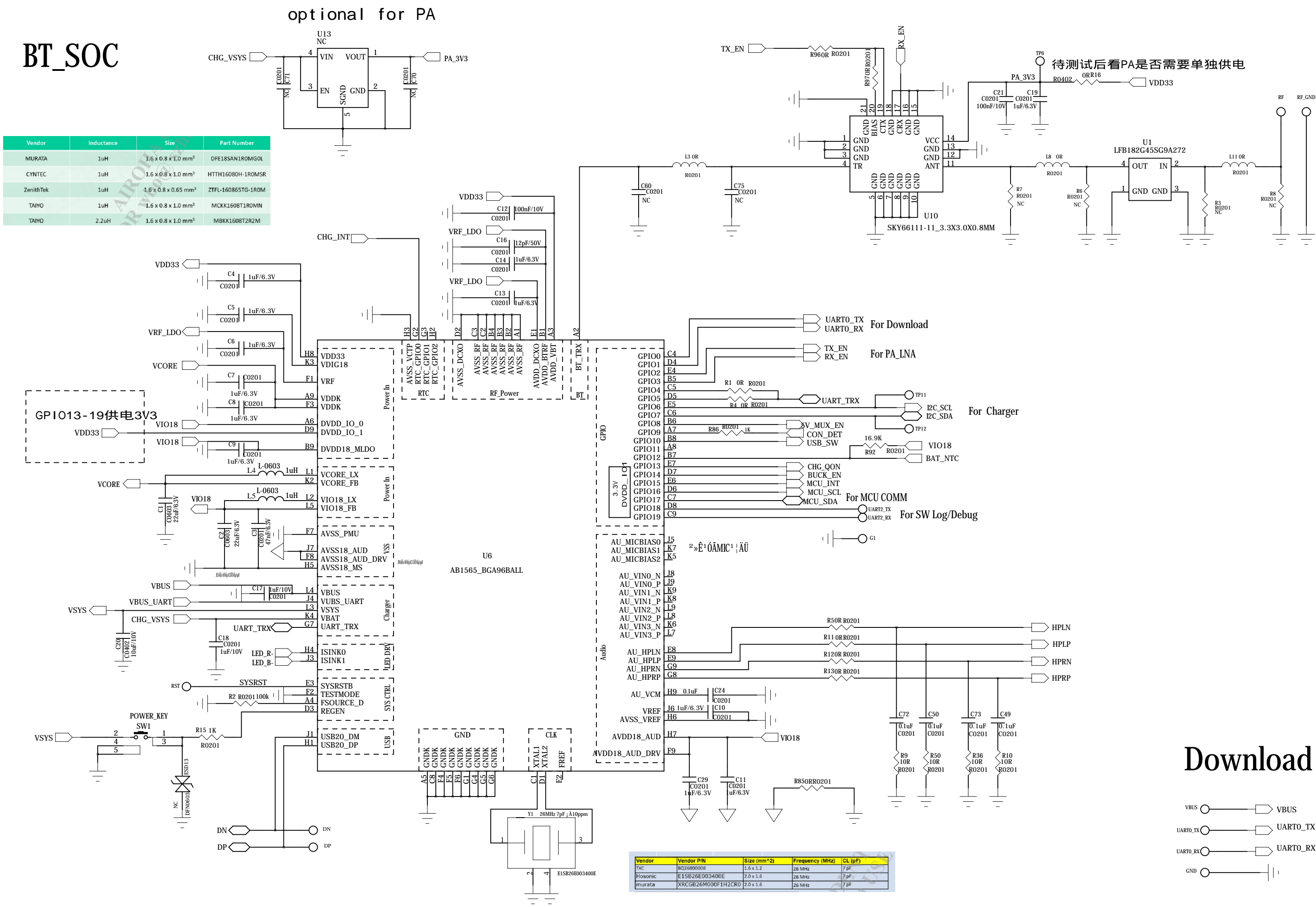
Project Name: WM301_RX

Drawn by: LTW/Bob	Date: 2023-05-12
-------------------	------------------

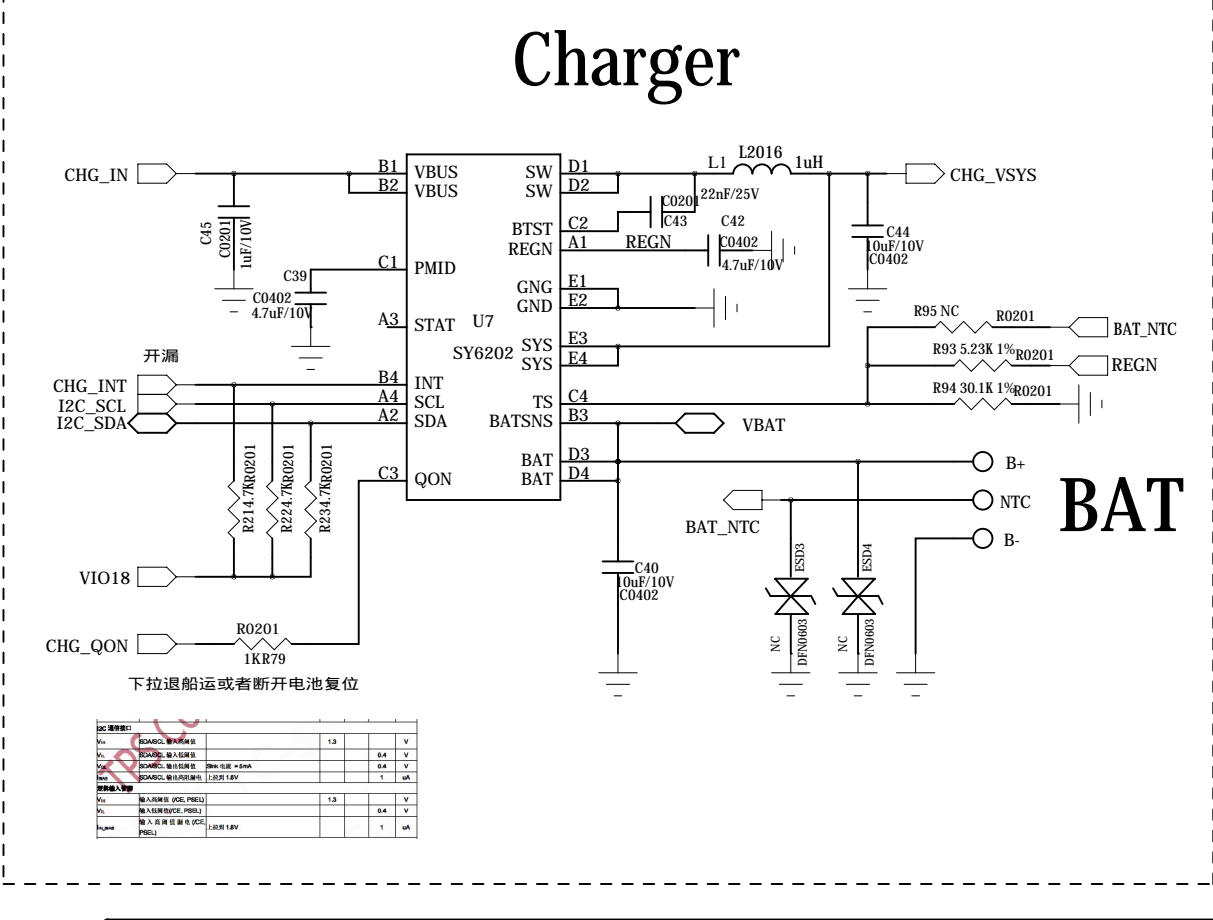
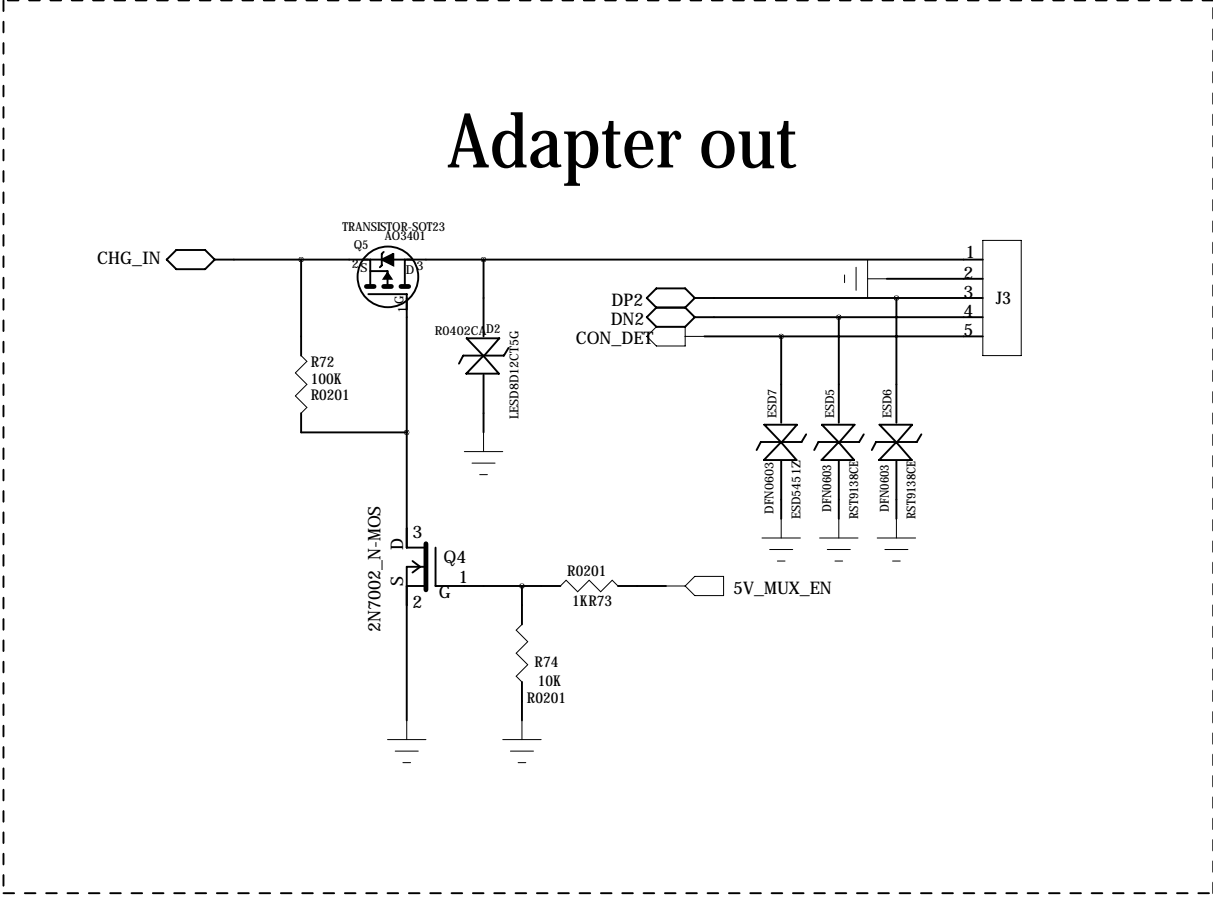
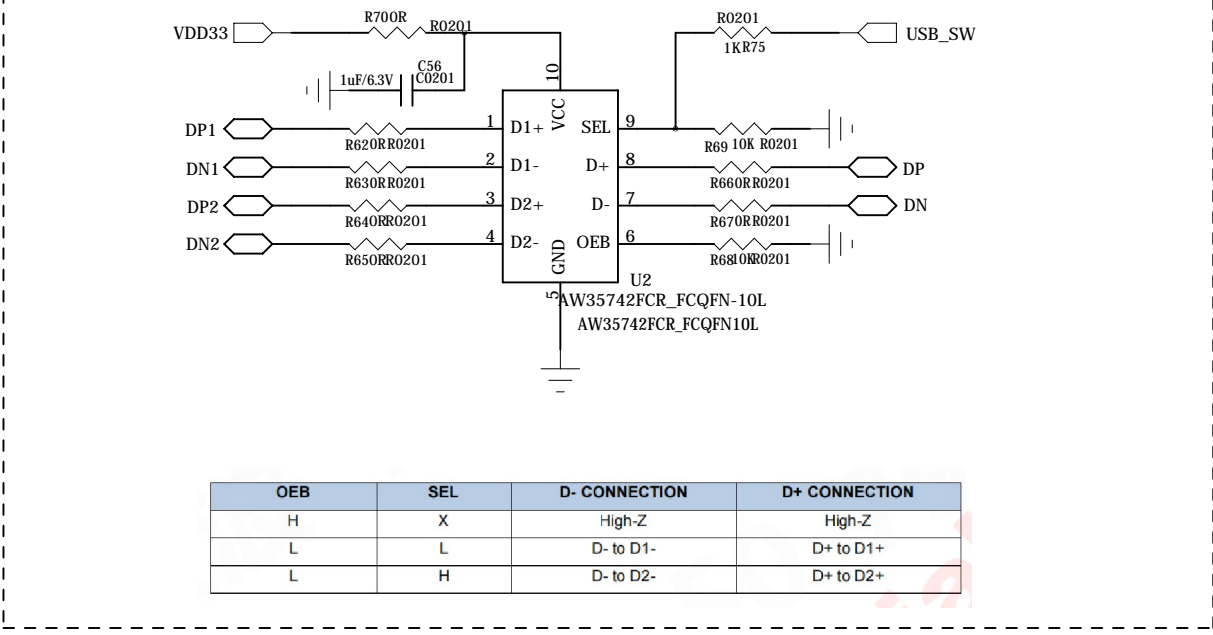
Sheet: 2 OF 4	Version: V1.0
---------------	---------------

BT_SOC

Vendor	Inductance	Size	Part Number
MURATA	1uH	1.6 x 0.8 x 1.0 mm ³	DPE18SAN1ROMGOL
CYNTEC	1uH	1.6 x 0.8 x 1.0 mm ³	HTH16080H-1ROMSR
ZenithTek	1uH	1.6 x 0.8 x 0.65 mm ³	ZTFL-160865TG-1ROM
TAIYO	1uH	1.6 x 0.8 x 1.0 mm ³	MCKK1608T1ROMN
TAIYO	2.2uH	1.6 x 0.8 x 1.0 mm ³	MBKK1608T2R2M

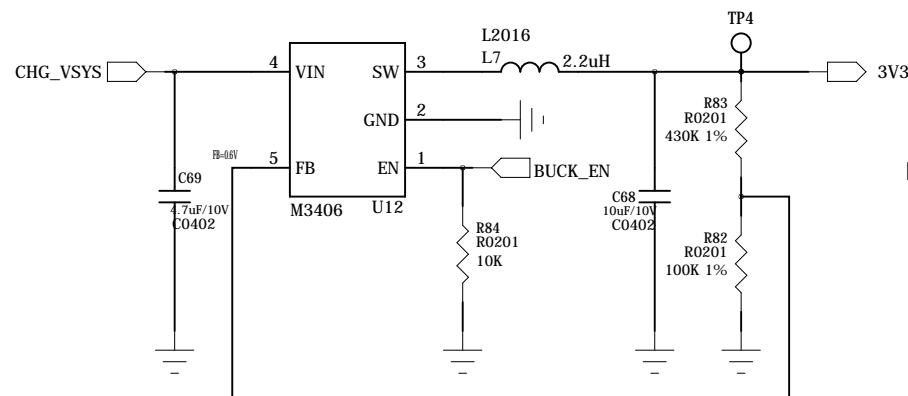


DP/DM_SW

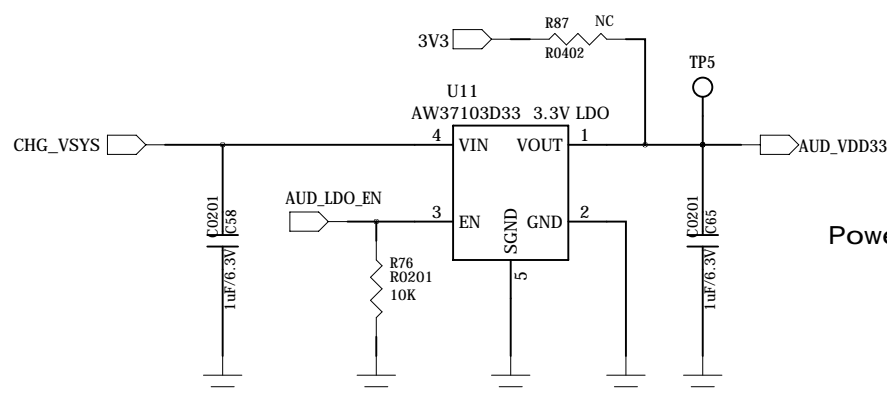


Company: <Company>	
Project Name: WM301_RX	
Drawn by: LTW/Bob	Date: 2023-05-12
Sheet: 1 OF 4	Version: V1.0

Power

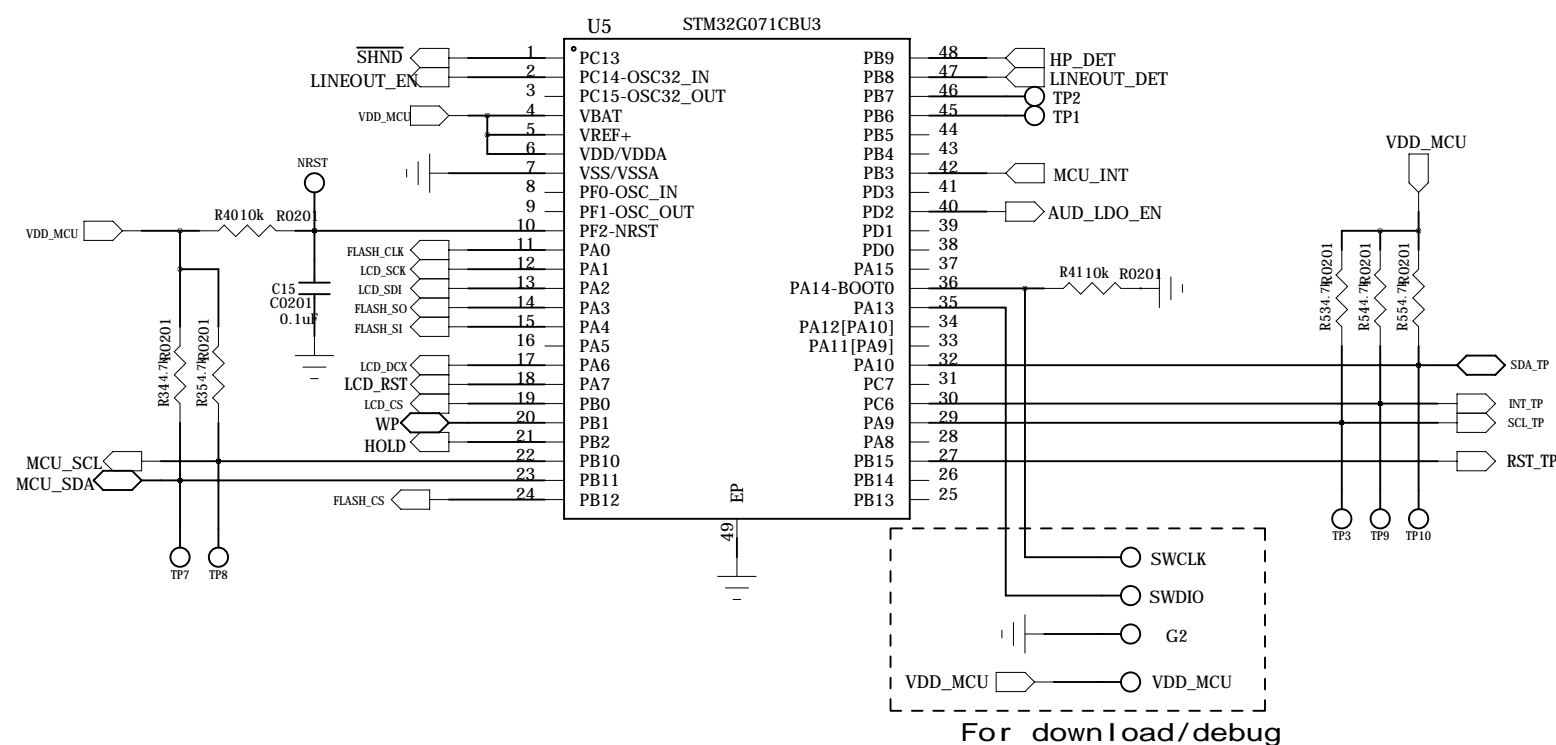
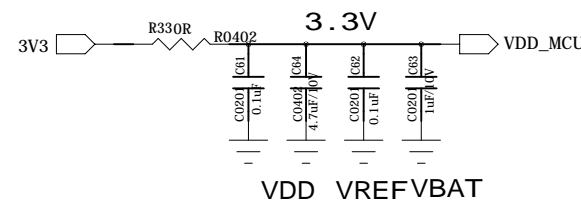


Power for:
MCU
Display
Touch

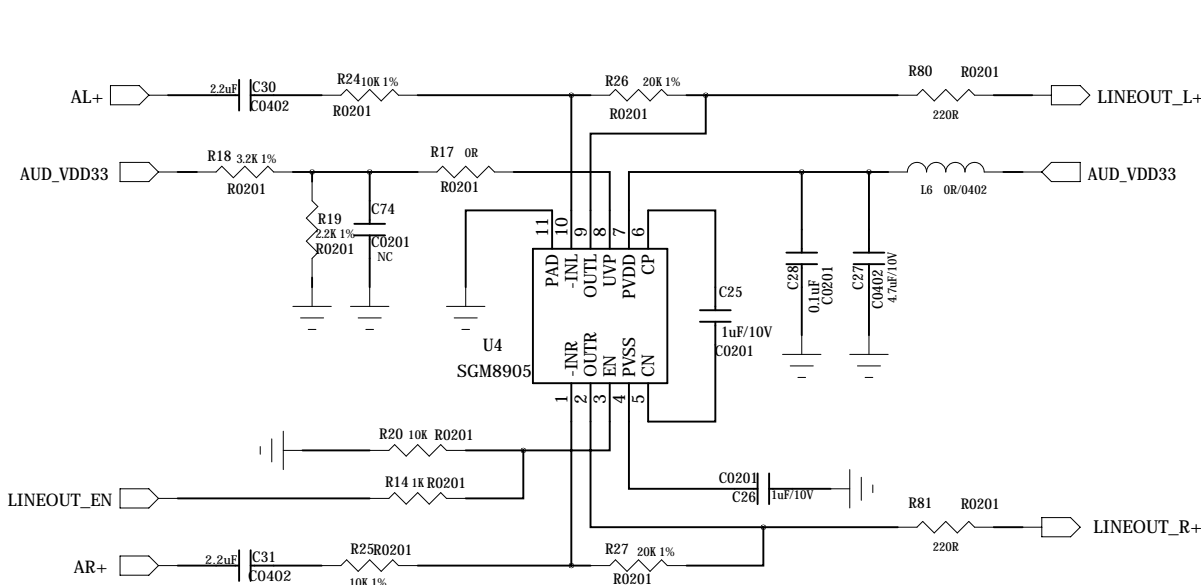


Power for:
HP AMP
Lineout

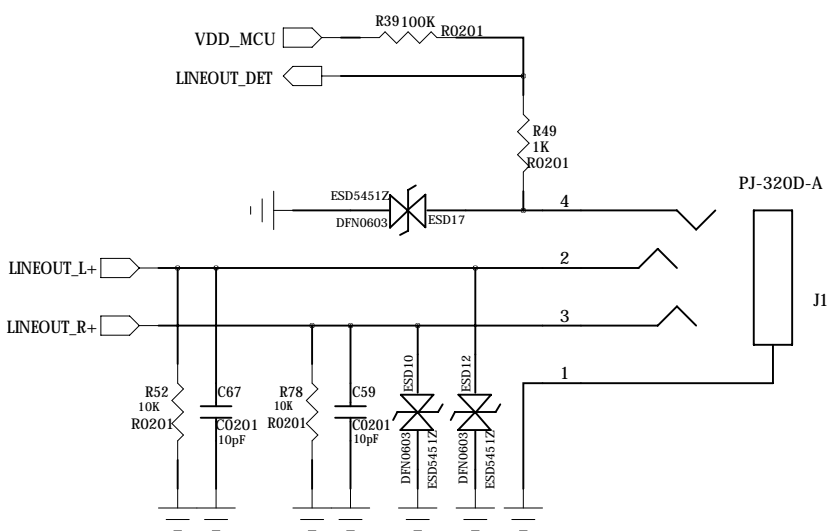
MCU



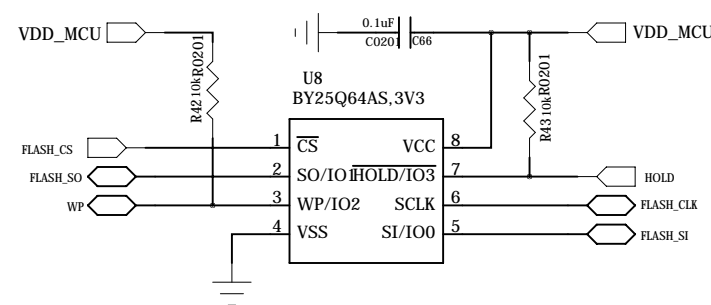
Line out



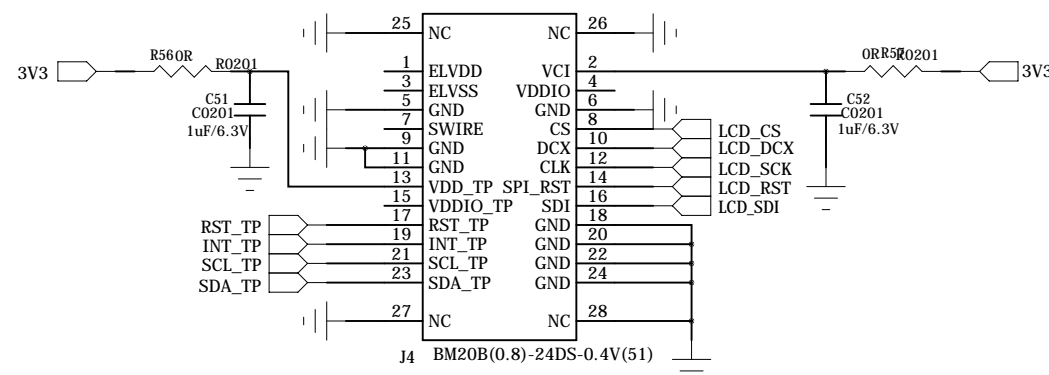
2V/V



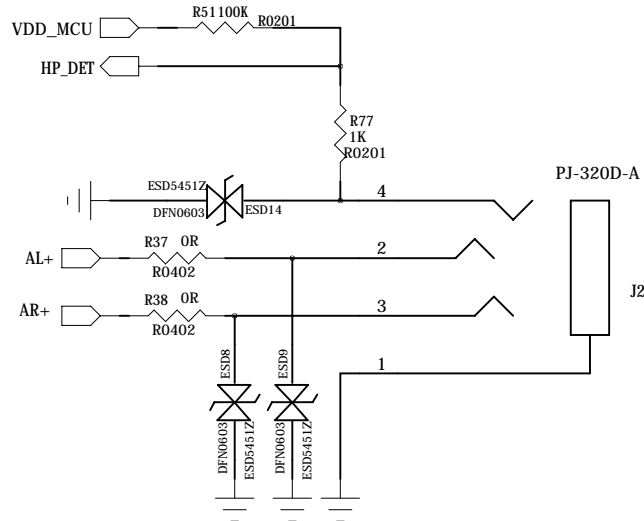
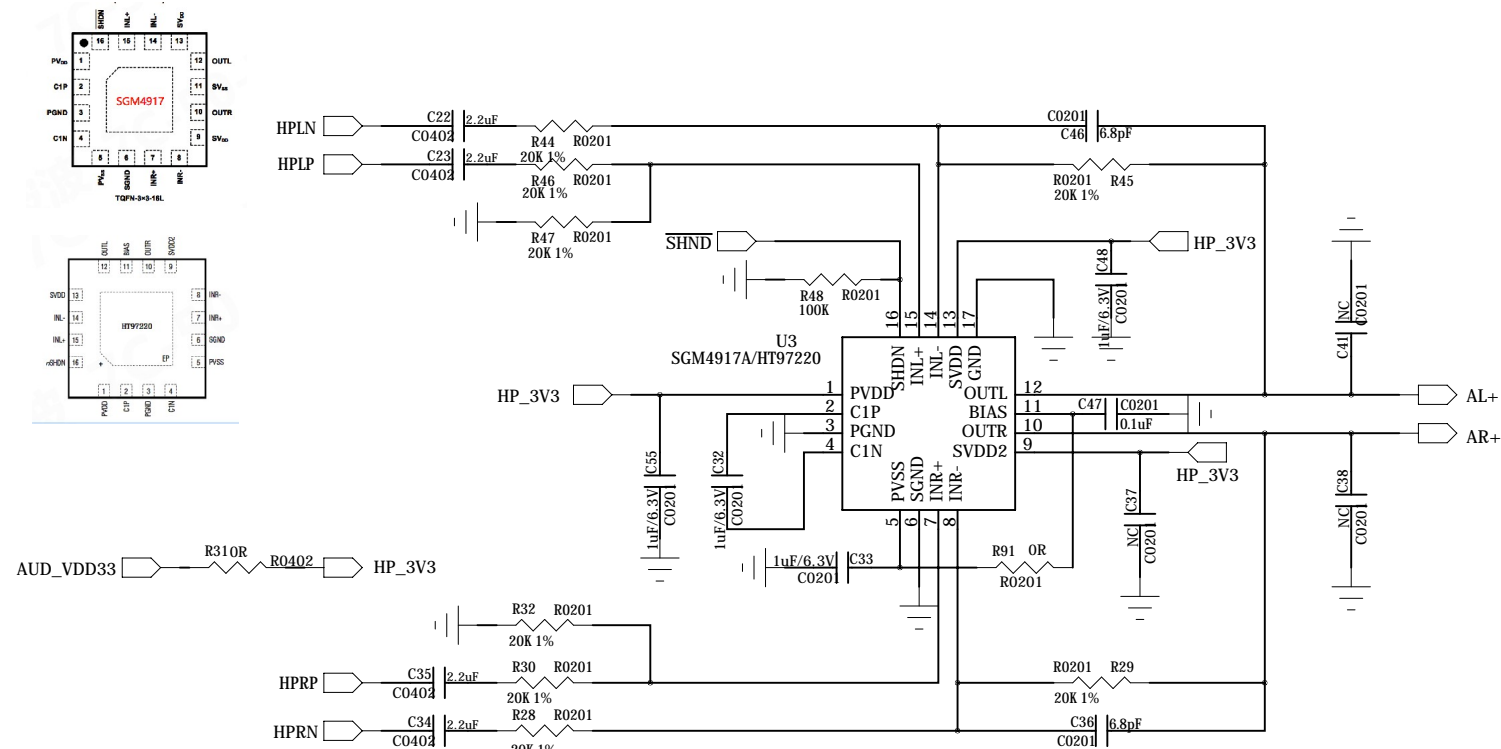
Flash



LCD



Headset out



Company: <Company>

Project Name: WM301_RX

Drawn by: LTW/Bob

Date: 2023-05-12

Sheet: 4 OF 4

Version: V1.0